

### **ENGINEERING DEPT.**

# **PRODUCT SPECIFICATION**

SPEC.NO.: SPCU005G

For Mini USB Receptacle Connector

**PAGE: 1/5** 

1. SCOPE:

**REVISIONS** 

This specification covers performance, tests and quality requirements for Universal Serial Bus (USB) plug and receptacle connectors. These connectors are cable mounted plug and PC Board mounted receptacle connectors

2. APPLICABLE STANDARDS:

EIA - 364	Test methods for electrical connectors
MIL - STD - 202	Methods for test of connectors for electronic equipment

- 3. APPLICABLE SERIES NO.: CU04
- 4. SHAPE, CONSTRUCTION AND DIMENSIONS See attached drawings

ECNT120312

- 5. MATERIALS See attached drawings
- 6. ACCOMMODATED P.C.BOARD 6.1 Thickness: 1.6 mm (.063") 6.2 P.C. Board Layout: See attached drawings



REVIEWED : <u>Eisley</u> APPROVED : <u>Sun</u> VERIFIED : <u>Eric</u> .



ENGINEERING DEPT.REVISIONSECNT120312

**PRODUCT SPECIFICATION** For Mini USB Receptacle Connector SPEC.NO.: SPCU005G

**PAGE: 2/5** 

# 7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1A 30V AC (r.m.s.)
7.2	Contact resistance	EIA 364 - 23 Subject mated contacts assembled in housing to 20 mV max. open circuit at 100 mA max.	$50 \text{ m}\Omega \text{ max}.$
7.3	Dielectric strength	EIA 364 - 20 Test between adjacent contacts of mated and unmated connector assemblies	100 VAC at sea level
7.4	Insulation resistance	EIA 364 - 21 Test between adjacent contacts of mated and unmated connector assemblies	100 MΩ min.
7.5	Capacitance	EIA 364 - 30 Test between adjacent circuits of unmated connectors at 1 KHz	2 pF max.

#### 8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION		REQUIREMENT
8.1	Contact retain force in insulator	Retention speed 25± 3 mm per minute from insulator		Plug: 0.5 Kgf min. Receptacle: 0.3 Kgf min.
8.2	Mating force	EIA 364 - 13 Measure force necessary to mate corresponding connector assemblies at maximum rate of 12.5 mm per minute		3.57 Kgf (35N) max.
8.3	Unmating force	EIA 364 - 13 Measure force necessary to unmate corresponding connector assemblies at maximum rate of 12.5 mm per minute		0.30 Kgf (3N) min.
8.4	Durability	EIA 364 - 09 Mate and unmate up to 5000 cycles repeatedly at maximum rate of 200 cycles per hour.	Mating Force Un-Mating Force	1~5000 Cycles 35N (3.57kgf)maximum 1~5000 Cycle 3N(0.30kgf) minimum



**ENGINEERING DEPT.** REVISIONS ECNT120312

**PRODUCT SPECIFICATION** For Mini USB Receptacle Connector SPEC.NO.: SPCU005G

**PAGE: 3/5** 

# 9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION		REQUIREMENT
9.1	9.1 Vibration EIA 364 - 28 Mate connectors and subject to the following vibration conditions (refer to 6 clause), for a period of 15 minutes in each of 3 mutually perpendicular axes, passing DC 100mA during the test.	Appearance	No Damage	
		clause), for a period of 15	Contact Resistance	50 milliohms maximum
		perpendicular axes, passing DC	Discontinuity	1.0 microsecond maximum
9.2	9.2 Shock	EIA 364 - 27 Mate connectors and subject to the following shock conditions. 3 shocks shall be applied along 3 mutually	Appearance	No damage
		perpendicular axes, passing DC 100mA current during the test.(Total of 18 shocks)	Contact Resistance	50 milliohms maximum
		Test pulse: Half Sine Peak value: 294m/s(30G) Duration: 11ms	Discontinuity	1.0 microsecond maximum
9.3	Solder ability	Tin-Lead Process		Minimum:
		Soldering time: $5 \pm 0.5$ second		90% of immersed area
		Soldering pot: 230 ± 5 °C Lead-Free Process		
		Soldering time: $3 \pm 0.5$ second Soldering pot: $245 \pm 5$ °C		
9.4			No damage	
			11.1)	
		Refer Reflow temperature profile(11.2)		



ENGINEERING DEPT. REVISIONS ECNT120312 **PRODUCT SPECIFICATION** For Mini USB Receptacle Connector SPEC.NO.: SPCU005G PAGE: 4/5

	ITEM	TEST CONDITION	I	REQUIREMENT
9.5	Salt spray	Temperature: $35 \pm 3 ^{\circ}$ CSolution: $5 \pm 1\%$ Spray time: $48 \pm 4$ hours(Stamping before plated)Spray time: $24 \pm 4$ hours(Stamping after plated)Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed.The specimens shall be suspended from the top using waxed twine, string or nylon thread.The test only define the plating area, without plating area (as copper cross section) will not be defined.EIA 364-26B / MIL-STD-202 Method 101)		Appearance: No damage on function Contact resistance: Less than twice of initial
9.6	connectors and expose to humidity in 7 cycles at 7 clau Upon completion of the expo period, the test specimens sh be conditioned at ambient ro	EIA 364 - 31 Method III Mate connectors and expose to humidity in 7 cycles at 7 clause. Upon completion of the exposure	Appearance Contact Resistance	No Damage 50 milliohms
		period, the test specimens shall be conditioned at ambient room conditions for 1 to 2 hours, after	Dielectric Strength	maximum Must meet 7-3
		which the specified measurements shall be	Insulation Resistance	Must meet 7-4

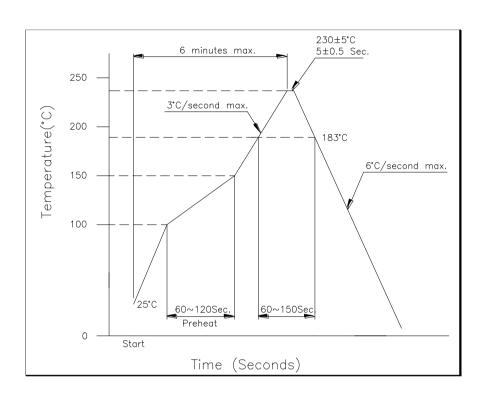
10. AMBIENT TEMPERATURE RANGE: -40°C to 60°C storage; 0°C to 40°C operating



ENGINEERING DEPT.PRODUCT SPECIFICATIONSPEC.NO.:SPCU005GREVISIONSECNT120312For Mini USB Receptacle ConnectorPAGE: 5/5

11. Recommended IR Reflow Temperature Profile:

11.1 Using Typical Solder Paste



### 11.2 Using Lead-Free Solder Paste

